MARKED-UP CLAIMS

Please amend claim 1 as follows:

1. A semiconductor manufacturing apparatus for processing a substrate surface, said apparatus comprising:

a vacuum vessel having a vacuum vessel plate [and a substrate stage];

[at least one] a substrate stage [is] provided on said vacuum vessel plate, said substrate stage having a substantially constant vertical position;

a cylinder [is] installed surrounding said substrate stage, [; the] a gap existing between said cylinder and said vacuum vessel plate, said gap being [is] made variable by lifting/lowering said cylinder[;] ,said cylinder having a cylinder interior space and a cylinder exterior space associated therewith, said cylinder interior space defining a processing chamber for processing said substrate surface, said cylinder exterior space including a transport chamber for transferring said substrate;

at least one cylinder lifting/lowering mechanism [per one] being operatively associated with said cylinder [is provided, in order to separate a space inside said cylinder comprising a processing chamber for processing said substrate surface from a space outside said cylinder including a transport chamber for

transferring said substrate];

[said transport chamber provided with] a substrate conveyer mechanism provided with said transport chamber, said substrate conveyer mechanism for transferring said substrate between said processing chamber and said transport chamber through said gap;

said processing chamber [is] being provided with a processing chamber gas inlet and a processing chamber gas outlet; and

said transport chamber [is] being provided with a transport chamber gas inlet and a transport chamber gas outlet.

Please amend claim 2 as follows:

2. A semiconductor manufacturing apparatus for processing a substrate surface, the apparatus composed of a vacuum vessel with a top and bottom plate, said apparatus comprising:

a plurality of substrate stages [are] provided on said vacuum vessel bottom plate, each of said substrate stages having a substantially constant vertical position;

a plurality of cylinders provided respectively with an O ring [are connected to said bottom plate through [a] bellows so as to surround said substrate stage, said cylinders forming a gap with said vacuum vessel top plate, a [; the] gap between said cylinder and said vacuum vessel top plate [is] being made variable by lifting/lowering said cylinder, and at a position where said gap becomes minimum, a plurality of cylinder

lifting/lowering mechanisms operatively associated with [per one] said cylinder [are] being provided, in order to hermetically separate [a] an interior space inside said cylinder [for creating] from an exterior space outside thereof, said interior space forming a processing chamber for processing said substrate surface, the exterior space defining a [with said O ring from a space outside said cylinder for creating a] transport chamber for transferring said substrate;

said transport chamber [is] being provided with a substrate conveyer mechanism for transferring said substrate between said processing chamber and said transport chamber through said gap;

said processing chamber [is] being provided with a processing chamber gas inlet and a processing chamber gas outlet; and

said transport chamber [is] being provided with a transport chamber gas inlet and a transport chamber gas outlet.

Please amend claim 11 as follows:

11. The semiconductor manufacturing apparatus according to Claim 10, wherein said plasma generation mechanism radiates microwave [thorough] energy through a slot antenna.